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(54) **HEAT-FLOW SENSOR**

WÄRMEFLUSSSENSOR

CAPTEUR DE FLUX THERMIQUE

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Description

FIELD OF THE INVENTION

5 **[0001]** The invention relates to a heat-flow sensor, a method of measuring the temperature of a subject using a heat-flow sensor, and a temperature sensing arrangement.

BACKGROUND OF THE INVENTION

10 **[0002]** Core body temperature (CBT) is an important vital sign in medical environments. A patient under anaesthetic is unable to regulate his/her body temperature, and operating rooms are generally cooled to a low level. Hypothermia occurs when the body core temperature drops below 36°C to a potentially dangerous level. Surgical patients are often hypothermic upon leaving the operating room. Hypothermic patients run the risk of heart complications, especially during the first 24 hours after surgery, since hypothermia acts as a shock to the system. Other problems associated with
15 hypothermia are increased risk of infection and bleeding. For these reasons, the CBT is generally closely monitored during medical procedures, or during long-term monitoring of a recovering patient. Conventional methods can involve intrusive probes (oesophageal, rectal, urethral) or active heat-flow sensors that require heating elements and control loops to control the heating elements.

20 **[0003]** Passive heat-flow sensors that do not require heating elements have the advantage that they are less hazardous to the patient, and consume relatively little power. Passive heat flow sensors are known in the prior art, e.g. from US 2011/158284 A1, US 2006/173375 A1, Kitamura et al: "Development of a new method for the noninvasive measurement of deep body temperature without a heater", Medical Engineering & Physics, Butterworth-Heinemann, GB, vol. 32, n°1, October 2010, p. 1-6, as well as from US 2012/128024 A1. A conventional heat-flow sensor can only measure heat flow
25 in the outward direction, e.g. outward relative to the surface of the skin to which the sensor is applied. However, core body heat flows in all directions, not just outward from the body. Therefore, a conventional passive heat-flow sensor generally cannot measure core body temperature to the necessary degree of precision unless the sensors are well insulated (which increases the size of the sensor due to the surrounding insulation). Another problem is that the contact area between body and sensor is rarely thermally uniform, particularly since the contact area of the sensor generally needs to be quite large. For example, the temperature profile over a patient's head can exhibit significant differences
30 on account of the positions of the arteries below the skin. A passive heat-flow sensor of the conventional type using two or more vertical thermistor arrangements can provide inaccurate temperature measurements due to poor adhesion of the sensor to the skin, or due to an air pocket between sensor and skin. Such a situation may arise in the case of a wearable sensor worn by a patient while moving around. Furthermore, a conventional heat-flow sensor is quite sensitive to ambient temperature changes.

35 **[0004]** Therefore, it is an object of the invention to provide an improved heat-flow sensor for measuring the temperature of a subject.

SUMMARY OF THE INVENTION

40 **[0005]** The object of the invention is achieved by the passive dual heat-flow sensor of claim 1. According to an example which is not part of the present invention, a heat-flow sensor comprises a contact face for placement on a subject during a temperature monitoring procedure. The heat-flow sensor comprises a plurality of combined thermistor arrangements, each comprising an inner thermistor (arranged at an inner face of the sensor) and an upper thermistor (arranged at the upper surface of the sensor) and arranged relative to the inner thermistor to measure a vertical heat flow outward from
45 the subject, i.e. to measure heat flow between the inner thermistor and the upper thermistor; and also a lateral thermistor arranged relative to the inner thermistor to measure a horizontal heat flow along the contact face, i.e. to also measure heat flow between the inner thermistor and the lateral thermistor.

50 **[0006]** The geometrical terms used in the claims relate to an assumed horizontal plane representing the outer surface of the subject and serve only to define a reference space. A "horizontal heat flow" is therefore any heat flow along the surface of the subject, and a "vertical heat flow" is any heat flow outward from the surface of the subject. It shall be understood that, in reality, a heat-flow sensor can assume any orientation when attached for example to the skin of a patient.

55 **[0007]** In the context of the invention, the arrangement of one thermistor relative to another is to be understood to mean that these two thermistors are essentially aligned in the direction along which a heat flow is to be measured. Here also, the geometrical terms "upper", "inner" and "outer" are used in the context of the reference space. Therefore, it will be understood that an inner thermistor is arranged at an inner face of the sensor, and an upper thermistor is arranged towards an outer surface of the sensor, such that an upper thermistor is vertically in line with an inner thermistor to measure a heat flow outward from the subject. The outward heat flow is in a direction from an inner thermistor to an

upper thermistor when the subject is warmer than the sensor; when the subject is cooler than the sensor the heat flow direction is in reverse. Similarly, it will be understood that a lateral thermistor is arranged in line with an inner thermistor to measure a heat flow along the surface of the subject, for example along the patient's skin. The lateral heat flow is in a direction between the inner thermistor and the lateral thermistor and serves to detect any difference in temperature between the inner sensor region and the side of the sensor containing the lateral thermistor.

[0008] An advantage of the heat-flow sensor is that the combination of a lateral heat flow monitor with the usual vertical heat flow monitor allows a much more precise temperature measurement, particularly since the lateral heat flow is explicitly measured, instead of only being estimated (as is the case for some conventional heat-flow sensors). The core body temperature of the subject - for example a patient during and after surgery - can be determined to a much greater degree of precision, so that critical situations such as hypothermia can be detected and dealt with in a timely manner.

[0009] The method of measuring the temperature of a subject using such a passive heat-flow sensor comprises the steps of placing the contact face of the heat-flow sensor on the subject during a temperature monitoring procedure; receiving temperature measurements collected by at least one combined thermistor arrangement of the heat-flow sensor; and calculating the temperature of the subject from the temperature measurements.

[0010] The method can deliver favorably precise results on account of the additional information provided by the lateral heat flow monitor of the combined thermistor arrangement in the inventive heat-flow sensor. This can be very advantageous in situations for which a precise temperature monitoring is required, for example to provide medical personnel with precise information regarding a patient's core body temperature, for example in an emergency situation requiring rapid decision-making.

[0011] The temperature sensing arrangement comprises such a heat-flow sensor and an evaluation unit arranged to receive temperature measurement values from the thermistors and to calculate the temperature of the subject on the basis of the temperature measurement values.

[0012] In the context of the invention, the term "subject" can relate to any living being. Critical thermal conditions generally arise in the context of operative situations, emergency medical situations, etc. in which a human patient may enter a state of hypothermia or hyperthermia. Therefore, without restricting the invention in any way, the terms "subject" and "patient" may be regarded as synonymous in the following. The term "heat-flow sensor" as used in the following in the context of the invention may be assumed to refer to a passive heat-flow sensor. Preferably, the passive heat-flow sensor is made of a foam material, and the outer surface of the inventive heat-flow sensor is uniformly exposed to the ambient surroundings. A uniform layer of a suitable material in place over the sensor may be used to protect the sensor from damage. However, it should be understood that any thermal influence of such a protective layer will apply in equal measure to each upper thermistor. In other words, the upper thermistors of the inventive passive heat-flow sensor are arranged to be influenced uniformly by the ambient surroundings.

[0013] A thermistor is a device whose electrical resistivity changes in response to a change in temperature, and can be embedded in the material of a heat-flow sensor. A thermistor can be realized as a component with two electrical connectors so that it can be included in an appropriate circuit. A temperature change is registered as a change in current or voltage, depending on the circuit realization. A thermistor component can also be realized as a compact integrated circuit (IC) device.

[0014] As indicated in the introduction, passive heat-flow sensors using one or more vertical arrangements of thermistor pairs are known from the prior art. The inventive heat flow sensor extends the sensitivity of the temperature measurement by also detecting and measuring a lateral heat flow along the surface of the patient, and the patient's temperature is deduced from the vertical heat flow and lateral heat flow measurements. The heat-flow sensor may be referred to simply as an enhanced heat-flow sensor in the following. In the following, the terms "combined thermistor arrangement" and "enhanced thermistor arrangement" may therefore be used interchangeably. Similarly, the terms "thermistor arrangement" and "thermistor configuration" may be used interchangeably. The term "temperature measurement value" is to be understood as the quantity reported by a thermistor to an evaluation unit, while the term "temperature measurement" relates to the sensed temperature of the subject, i.e. the temperature reported by the evaluation unit of a heat-flow sensor or by the evaluation unit of a temperature sensing arrangement.

[0015] The thermal resistivity of the intervening path between two thermistors (inner thermistor and upper thermistor; inner thermistor and lateral thermistor) is determined by structural properties of the temperature monitor such as the material of the sensor and the thickness of the sensor. The thermal resistivity can be measured and can be a known quantity.

[0016] For accurate temperature sensing, any inner thermistor of the inventive heat-flow sensor is preferably close to or coincident with the contact face of the sensor. Similarly, any lateral thermistor of an enhanced thermistor configuration is preferably positioned towards an outer region of the sensor and also close to or coincident with the contact face of the sensor. Any upper thermistor is preferably close to the "uppermost" surface of the sensor, i.e. its outside surface when attached to the subject.

[0017] The thermistors can be connected via wire connections to an evaluation unit. For example, temperature measurement values can be received by an evaluation unit connected to the sensor by a cable connection. In another preferred

embodiment of the invention, the sensor can be equipped with an interface for transmitting the temperature measurement values wirelessly to the evaluation module. The sensor may also incorporate an analog-to-digital converter to convert analogue measurement values into digital values for data transmission. The heat-flow sensor of the temperature sensing arrangement can preferably be realized as a wearable device, i.e. a patient can wear the heat-flow sensor for a long-term temperature monitoring interval. An evaluation unit of the inventive temperature sensing arrangement can preferably be realized as a portable device. For example, the patient or any medical personnel can use a hand-held device with a display such as a tablet computer or smart-phone to observe temperature development. In a wearable realization, results of temperature monitoring can be shown on the display of a smart watch or similar device. The temperature sensing arrangement can be incorporated in a patient support device such as an operating table in a surgical operating theatre, a mattress of a hospital bed, an, infant sleeping bag or incubator of a neonatal ward, etc.

[0018] Advantageously, a single inner thermistor is used, and this is connected to an upper thermistor and also to a lateral thermistor to achieve the favorable side compensation for accurate estimation of deep body temperature. During a temperature monitoring interval, the temperatures of the three thermistors are observed. The deep body temperature T_{db} (core body temperature) can be expressed as:

$$T_{db} = T1 + \left[\frac{\frac{T1 - T2}{RV} + \frac{T1 - T3}{RH}}{R_B} \right] \quad (1)$$

where T1 is the temperature at the inner thermistor; T2 is the temperature at the upper thermistor; T3 is the temperature at the lateral thermistor; RV is the "vertical" thermal resistivity between inner thermistor and upper thermistor; and RH is the "horizontal" thermal resistivity of the electrical connection between inner thermistor and lateral thermistor. R_B is the thermal resistivity of the body to which the sensor is applied, for example skin thermal resistivity. The thermal resistivity of a patient's skin can be estimated, or an already established value can be used by default.

[0019] An inner thermistor, common to both vertical and lateral thermistor pairs of an enhanced thermistor configuration, can be located near the center of the sensor, preferably as close as possible to the contact surface. This arrangement may be preferred for a straightforward realization of the heat flow sensor that comprises only a single enhanced thermistor configuration. Such an "enhanced single heat-flow sensor" can provide temperature measurements relating to the outward heat flow from the patient, enhanced or augmented by temperature measurements in one lateral direction along the patient's skin. This configuration already enables a relatively accurate estimation of the patient's core body temperature.

[0020] The heat-flow sensor can comprise only such enhanced thermistor arrangements. These can be separate and distinct from each other. Equally, the heat-flow sensor can comprise multiple vertical thermistor pairs, giving a configuration of enhanced thermistor arrangements, each comprising a vertical thermistor pair and the lower thermistor of a neighboring pair. Alternatively, the enhanced thermistor arrangements share a single inner thermistor and a single upper thermistor. This enhanced single heat-flow sensor measures heat flow in one vertical direction through the inner and upper thermistors, and augments the vertical heat flow information by additional information obtained by measuring heat flow in several sideways or lateral directions, whereby each lateral direction effectively passes through the inner thermistor and one lateral thermistor. By incorporating more than one lateral thermistor, it is possible to monitor heat flow in more than one lateral direction, allowing a better estimation of the thermal behavior of the area under the sensor contact surface. The lateral thermistor of a combined thermistor arrangement can be a solitary thermistor arranged at the contact face; alternatively the lateral thermistor of a combined thermistor arrangement can be the inner thermistor of a vertical thermistor pair.

[0021] Advantageously, in addition to its enhanced thermistor arrangement(s), the heat-flow sensor comprises a separate vertical thermistor arrangement with a further inner thermistor and a further upper thermistor arranged relative to that inner thermistor to measure a further vertical heat flow outward from the subject. This additional vertical thermistor arrangement is functionally independent of any combined thermistor arrangement, and such an embodiment may be referred to as an enhanced dual heat-flow sensor. Preferably, the vertical thermistor arrangement is positioned centrally in the heat-flow sensor. A centrally positioned and independent vertical thermistor arrangement can be flanked by a plurality of equidistantly arranged enhanced thermistor configurations, for example.

[0022] In an embodiment comprising a vertical thermistor arrangement and one enhanced thermistor arrangement, it is not necessary to know the thermal resistivity of the skin, since this term cancels out of the equation for deep body temperature T_{db} , which is now expressed as:

$$T_{db} = \frac{T1(TV1-TV2) + K \cdot TV1(T2-T1) + L \cdot TV1(T3-T1)}{TV1-TV2 + K(T2-T1) + L(T3-T1)} \quad (2)$$

where TV1 is the temperature at the inner thermistor of the vertical thermistor arrangement and TV2 is the temperature at the upper thermistor of the vertical thermistor arrangement; T1 is the temperature at the inner thermistor of the enhanced heat-flow thermistor arrangement, T2 is the temperature at the upper thermistor of the enhanced thermistor arrangement, and T3 is the temperature at the outer or lateral thermistor of the enhanced thermistor arrangement. K and L are scalar values. The value K is expressed as:

$$K = -\frac{(TV1-TV2)(T1-T_{db})}{(-3T1+T2+2T3)(TV1-T_{db})} \quad (3)$$

[0023] The scalar value L is a ratio and can be expressed as:

$$L = \frac{RV2}{RH} \quad (4)$$

where RV2 is the thermal resistivity between inner and upper thermistors of the vertical thermistor arrangement; and RH is the thermal resistivity between inner and lateral thermistors of the enhanced thermistor arrangement.

[0024] In one exemplary embodiment, for which the vertical thermal resistivity RV of the enhanced thermistor arrangement is twice the horizontal thermal resistivity RH, equation (4) reduces to:

$$L = \frac{RV1}{RH} = \frac{RV1}{0.5RV} = \frac{2RV1}{RV} = 2K \quad (5)$$

[0025] This allows equation (2) to be solved for the value of deep body temperature T_{db} .

[0026] According to the present invention, invention, the heat-flow sensor comprises multiple enhanced thermistor arrangements. Similar equations on the basis of equations (2) - (5) above can be developed for embodiments of the inventive enhanced heat-flow sensors that two or more enhanced thermistor arrangements. The evaluation unit can comprise a microprocessor or functional equivalent, realized to execute one or more algorithms, based on the above equations that process the temperature measurement values delivered by the thermistors in order to compute a deep body or core temperature of the subject.

[0027] An advantage of measuring heat flow in more than one lateral direction is that it allows a precise temperature measurement even if the heat-flow sensor is not ideally or optimally in position. It can often be difficult to exactly determine a correct or ideal sensor placement, for example when a sensor is to be placed over the carotid artery. A slightly "off-center" placement could result in significant errors in temperature measurements when a prior art heat-flow sensor is used. An inventive heat-flow sensor with several enhanced thermistor configurations provides several candidate temperature measurement values, from which a more precise core body temperature can be deduced. For example, in a preferred embodiment of the invention, temperature measurements are received from a plurality of combined thermistor arrangements, and the temperature measurements are averaged before calculating the temperature of the subject. Equally, the maximum temperature value reported by a thermistor may be used for the calculation of lateral and vertical flows. For example, the temperature measurement values received from the sensor can be examined to identify the pair of inner and outer thermistors that shows the maximum vertical heat flow. This vertical thermistor pair will generally be characterized by the inner thermistor that has the greatest temperature measurement value, for example. Then, the vertical thermistor pairs (or the lateral thermistors) that neighbor that "maximum vertical flow" thermistor pair are identified. Their temperature measurement values are then used to establish a lateral heat flow outward from the "maximum vertical flow" thermistor pair.

[0028] Another advantage of using several enhanced thermistor configurations is given by the ability to identify an enhanced thermistor configuration that is sub-optimally placed to measure temperature. The inventive method preferably comprises the steps of comparing temperature measurements from a plurality of enhanced thermistor configurations; identifying an enhanced thermistor configuration that is providing unreliable temperature measurement values; and discarding those temperature measurement values.

[0029] For example, a situation might arise in which the sensor is not ideally attached to the skin of the patient. In a heat-flow sensor with three or more equidistantly arranged enhanced thermistor configurations, any significant difference

between the values delivered by the enhanced thermistor configurations can be identified. If one of the enhanced thermistor configurations delivers values that are significantly different from the values delivered by the other enhanced thermistor configurations, and if the values delivered by the other enhanced thermistor configurations are relatively similar, this would indicate that the sensor is not adequately attached to the skin. Any thermistor delivering outlier or non-conformant values is preferably disregarded so that its data does not falsify computation of the core body temperature.

[0030] In both sensors when using the side thermometer the estimated CBT is less sensitive to environmental changes and gives good results, whereas the basic single and dual heat-flow CBT sensors without a side thermometer are sensitive to the environmental changes. Including a side thermistor improves the estimated CBT during a variation of the core body temperature as well as during a variation of environmental changes.

[0031] Other objects and features of the present invention will become apparent from the following detailed descriptions considered in conjunction with the accompanying drawings. It is to be understood, however, that the drawings are designed solely for the purposes of illustration and not as a definition of the limits of the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

[0032]

Fig. 1 is a schematic representation of a first example which is not part of the present invention;

Fig. 2 shows a plan view of the heat-flow sensor of Fig. 1 from below;

Fig. 3 shows a plan view of the heat-flow sensor of Fig. 1 from above;

Fig. 4 shows temperature curves relating to the heat-flow sensor of Fig. 1;

Fig. 5 is a schematic representation of a second example;

Fig. 6 shows a plan view of the heat-flow sensor of Fig. 5 from below;

Fig. 7 shows a plan view of the heat-flow sensor of Fig. 5 from above, showing a middle level;

Fig. 8 shows a plan view of the heat-flow sensor of Fig. 5 from above, showing a top level;

Fig. 9 shows temperature regions relating to the sensor of Fig. 5;

Fig. 10 shows temperature development of enhanced thermistor configurations in an inventive sensor of the dual heat-flow type;

Fig. 11 is a schematic representation of a third example;

Fig. 12 shows a plan view of the heat-flow sensor of Fig. 11 from below.

[0033] In the drawings, like numbers refer to like objects throughout. Objects in the diagrams are not necessarily drawn to scale.

DETAILED DESCRIPTION OF THE EMBODIMENTS

[0034] Fig. 1 shows a schematic cross-section through the heat-flow sensor 1, realized in this example as an enhanced single heat-flow sensor 1 of a temperature monitoring arrangement 10. This can be securely attached to the subject 8, for example to the skin of a patient 8. The outer surface 12 of the sensor is exposed to the surroundings and is not covered by any insulating material. A first thermistor S1 is arranged at an inner face of the sensor 1, and will lie in close contact to the patient's skin. A second thermistor S2 is arranged at the upper surface of the sensor 1. The thermal resistivity RV of the sensor 1 in the "vertical" direction, and the thermal resistivity RH of the sensor 1 in the "horizontal" direction are indicated by resistor symbols. A further resistor symbol indicates the thermal resistivity R_B of the body 8 to which the sensor 1 is attached.

[0035] Obtaining a temperature measurement at any one point in time using the sensor 1 involves collecting the temperature measurement values T1, T2, T3 from the thermistors S1, S2, S3 respectively (i.e. thermistor S1 delivers temperature measurement value T1, thermistor S2 delivers temperature measurement value T2 etc.) and calculating a sensed temperature using knowledge of the heat flux through the sensor 1. To compute the sensed temperature using the enhanced single heat-flow sensor 1, it is also necessary to determine or estimate the thermal resistivity R_B of the skin, which may vary from patient to patient. The sensed body temperature T_{db} may be calculated using equation (1) as already described above. To this end, the measurement values collected by the thermistors S1, S2, S3 are sent to an evaluation unit 2 of the temperature monitoring arrangement 10, for example over a cable connection or wirelessly. A microprocessor 3 of the evaluation unit 2 performs the necessary computations to arrive at the body temperature. A display 4 can show core body temperature development as time progresses. While the diagram only indicates one lateral thermistor for the sake of simplicity, any number of lateral thermistors S3 and vertical thermistor pairs S1, S2 can be implemented by such an enhanced single heat-flow sensor.

[0036] Fig. 2 shows a plan view of such a sensor from below, showing the positions of an inner thermistor S1 and lateral thermistors S3 on the contact face 11 of the sensor 1. In this exemplary embodiment, the sensor 1 comprises a

centrally positioned inner thermistor S1, and four equidistantly arranged lateral thermistors S3. Fig. 3 shows a plan view of the sensor 1 from above, indicating the position of the upper thermistor S2 of the enhanced thermistor configuration. The shape of the sensor does not have to be circular with a flat contact surface, as shown in the examples, but can be chosen to best fit the region on the body where the sensor is to be used.

[0037] Fig. 4 shows temperature curves obtained in a basic test setup, using a hotplate with a set point at 37°C, and a skin-like material with a thermal conductivity of 0.30 W/mK. A first curve 40 shows the temperature of the body measured using the inventive enhanced single heat-flow sensor, with a single enhanced thermistor arrangement. A second curve 41 shows the temperature measured using a conventional single heat-flow sensor (without any lateral compensation). The advantage of using the lateral thermistor can clearly be seen, since the temperature estimated using values provided by the enhanced thermistor arrangement reaches equilibrium faster, and is a closer match to the reference temperature.

[0038] Fig. 5 shows a schematic cross-section through a second example of the heat-flow sensor 1. Here, the sensor 1 comprises a lower layer and an upper layer, to achieve two different values of thermal resistivity RV, RV1 in the vertical or outward direction. The diagram shows an enhanced thermistor configuration with thermistors S1, S2, S3 as described in Fig. 1 above, and also an additional vertical thermistor configuration comprising a further inner thermistor SV1 and a further outer thermistor SV2. Here, thermistor SV1 delivers temperature measurement value TV1, and thermistor SV2 delivers temperature measurement value TV2. In this example, the temperature measurement values T1, T2, T3 from the enhanced thermistor configuration and the temperature measurement values TV1, TV2 from the additional vertical thermistor configuration are sent to an evaluation unit 2, which can be realized in a hand-held device such as a smartphone or tablet computer with a display 4. A microprocessor 3 of the hand-held device can compute the body temperature T_{db} using equations (2) - (5) as described above. In this exemplary embodiment, the sensor 1 comprises a wireless interface 5 for wireless transmission of the temperature measurement values T1, T2, T3, TV1, TV2 to the evaluation unit 2.

[0039] Fig. 6 shows a plan view from below of an enhanced dual-flow sensor 1 with four enhanced thermistor configurations about a central vertical thermistor configuration, indicating the position of the inner thermistor SV1 of the centrally positioned vertical thermistor configuration, the positions of the inner thermistors S1 and the lateral thermistors S3 of the four enhanced thermistor configurations. Fig. 7 shows a plan view from above the middle layer of the enhanced dual-flow sensor 1, indicating the positions of the upper thermistors S2 of the enhanced thermistor configurations. Fig. 8 shows a plan view from above the top layer of the enhanced dual-flow sensor 1, indicating the position of the upper thermistor SV2 of the centrally positioned vertical thermistor configuration. Temperature measurement values provided by the four enhanced thermistor configurations can be averaged to improve the accuracy of the sensed body temperature.

[0040] Fig. 9 shows a schematic representation of the temperatures corresponding to the thermistor arrangements of the enhanced dual-flow sensor of Figs. 6 - 8. Here, the relative temperatures of the various thermistor arrangements are indicated as shaded regions 90, 91, 92 of a matrix. The intensity of the shading is interpreted relative to the remaining neutral regions of the matrix. The temperature measured by the vertical thermistor arrangement is indicated by the central shaded region 90. Temperatures measured using data provided by the inner and upper thermistors of the enhanced thermistor arrangements are indicated by the shaded regions 92, while the temperatures measured using data provided by the inner and lateral thermistors of the enhanced thermistor arrangements are indicated by the shaded regions 91. The darker color of the shaded region at the upper right in the diagram indicates that this thermistor is in poor contact with the patient's skin. The evaluation unit can identify such a discrepancy in the temperature measurement values, and can choose to ignore temperature measurement values from a thermistor configuration that appears to be delivering erroneous or unreliable data.

[0041] Fig. 10 shows an exemplary temperature development plot of the enhanced thermistor arrangements described in Fig. 9 above. Curve 10A is exemplary of a temperature calculated on the basis of temperature measurement values from three enhanced thermistor arrangements of which the inner thermistors are in good contact with the patient's skin. Curve 10B is exemplary of a temperature calculated on the basis of temperature measurement values from a fourth enhanced thermistor arrangement of which the inner thermistors are in poor contact with the patient's skin. Owing to the persistent significant difference in the values, the evaluation unit would disregard the values provided by the fourth enhanced thermistor arrangement from the temperature calculation algorithm.

[0042] The final estimated core body temperature depends to a large extent on the geometry and thermal conductivity of the sensor. Experimental results have shown that even during sub-optimal conditions, the enhanced sensor performs very well. When applied to a reference body that is gradually heated, the temperature sensed using data provided by an enhanced single heat-flow sensor is a much closer match than the temperature sensed using data provided by the conventional single heat-flow sensor. Similarly, the temperature sensed by an enhanced dual heat-flow sensor according to the invention has been observed to be more precise than a comparable conventional dual sensor, which - although considered to be quite accurate - can report sensed temperatures that are off by about 0.4°C. This is considered to be a significant discrepancy regarding core body temperature, particularly when it is necessary to identify a tendency towards hypothermia or hyperthermia so that preventive measures can be taken to avoid a critical situation.

[0043] The improvement in accuracy of the enhanced heat-flow sensor is because it considers lateral heat flow also, and is therefore significantly less sensitive to variations in ambient temperature. The improvement in accuracy has been

observed for a reference body with a constant temperature at 37.5°C and a variation in the ambient or outside temperature from 0°C to 30° C. The body temperature as measured by the enhanced heat-flow sensor remains essentially constant for all values of ambient temperature, whereas a comparable conventional heat-flow sensor exhibits relatively poor performance particularly at the lower temperatures, The enhanced heat-flow sensor performs significantly better than

its conventional counterpart which does not.

[0044] Fig. 11 shows a further example of the passive heat-flow sensor, realized as a single heat-flow sensor and comprising vertical thermistor pairs S1, S2, giving a configuration of enhanced thermistor arrangements, each comprising a vertical thermistor pair S1, S2 and a lateral thermistor corresponding to the lower thermistor S1 of a neighboring vertical thermistor pair. To determine the core body temperature, the temperature measurement values of the thermistors S1, S2 are examined to identify the pair $V_{\max}$ with the maximum vertical heat flow. Of this vertical thermistor pair $V_{\max}$, the inner thermistor S1 and outer thermistor S2 will supply the values for T1 and T2 of equation (2) above. A value of T3 can be determined by obtaining the mean temperature of a neighboring vertical pair, for example the vertical pair V_{left} on the left of the "maximum vertical flux" pair $V_{\max}$ or the vertical pair V_{right} on the right, etc. by adding the temperature measurement values of the thermistors S1, S2 and halving the result. The most likely result can be chosen as the value for T3 in equation (2) above.

[0045] Fig. 12 shows a plan view of the single heat-flow sensor of Fig. 11, showing its contact face 11. The positions of the inner thermistors S1 are shown. The location of the thermistor pair $V_{\max}$ with the maximum vertical heat flow is indicated by the dotted line encircling the corresponding inner thermistor. The diagram shows that this thermistor pair $V_{\max}$ has four possible "neighbors" (two such pairs V_{left} , V_{right} were described in Fig. 11), any of which can be used to determine a value of T3 as described above. The advantage of being able to choose between multiple neighboring thermistors is that any erroneous temperature measurement values (arising from sub-optimal contact to the patient's skin, for example) can be identified and disregarded, as explained in Fig. 9 above.

[0046] Any suitable sensor shape may be used. Equally, different numbers of vertical and lateral thermistors can be incorporated in various examples of the enhanced heat-flow sensor. As described above, calculation of core temperature can be performed on the sensor or can be performed remotely. Results can be displayed locally (on a screen) or remotely on a smart watch, mobile phone or the display of any other suitable device. Furthermore, the principle of the invention can be used in an active sensor realization, for example by controlling a heating element to bring the sensor to a zero heat-flux state.

[0047] For the sake of clarity, it is to be understood that the use of "a" or "an" throughout this application does not exclude a plurality, and "comprising" does not exclude other steps or elements. The mention of a "unit" or a "module" does not preclude the use of more than one unit or module.

Reference signs:

[0048]

1	heat-flow sensor
2	evaluation unit
3	microprocessor
4	display
5	wireless interface
8	subject
10	temperature sensing arrangement
11	sensor contact face
12	sensor outer surface
10A, 10B	temperature curve
40, 41	temperature curve
90,91,92	matrix field
110, 111	temperature curve
120, 121	temperature curve
130, 131, 132	temperature curve
140, 141	temperature curve
R_B	body resistivity
RV, RV1, RH	thermal resistivity
S1, SV1	inner thermistor
S2, SV2	upper thermistor
S3	lateral thermistor
T_{db}	core body temperature

T1, T2, T3	temperature measurement value
TV1, TV2	temperature measurement value
$V_{\max}$	thermistor pair
$V_{\text{left}}, V_{\text{right}}$	thermistor pair

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Claims

- 10 1. A passive dual heat-flow sensor (1) comprising a contact face (11) for placement on a subject (8) during a temperature monitoring procedure;
 - a lower layer;
 - an upper layer;
 - 15 - a vertical thermistor arrangement (SV1, SV2) comprising an inner thermistor (SV1) arranged at the inner face of the lower layer of the sensor (1) and an upper sensor (SV2) arranged at an upper surface of the upper layer of the sensor (1); and
 - a plurality of combined thermistor arrangements, wherein a combined thermistor arrangement comprises
 - 20 - an inner thermistor (S1) arranged at an inner face of the lower layer of the sensor (1);
 - an upper thermistor (S2) arranged at the upper surface of the lower layer of the sensor (1) and arranged relative to the inner thermistor (S1) to measure a vertical heat flow outward from the subject (8); and
 - a lateral thermistor (S3) arranged in line with the inner thermistor (S1) to measure a horizontal heat flow along the contact face (11).
- 25 2. A passive dual heat-flow sensor according to claim 1, comprising at least four combined thermistor arrangements.
3. A passive dual heat-flow sensor according to claim 1 or claim 2, comprising a plurality of vertical thermistor pairs (S1, S2), wherein a vertical thermistor pair comprises an inner thermistor (S1) and an upper thermistor (S2).
- 30 4. A passive dual heat-flow sensor according to any of the preceding claims, wherein the outer surface (12) of the sensor (1) is exposed.
5. A passive dual heat-flow sensor according to claim 1, wherein the vertical thermistor arrangement (SV1, SV2) is positioned centrally in the heat-flow sensor (1).
- 35 6. A method of measuring the temperature of a subject (8) using a passive heat-flow sensor (1) according to any of claims 1 to 5, which method comprises the steps of
 - placing the contact face (11) of the passive heat-flow sensor (1) on the subject (8) during a temperature monitoring procedure;
 - 40 - receiving temperature measurement values (T1, T2, T3, TV1, TV2) collected by the thermistors (S1, S2, S3, SV1, SV2) of the passive dual heat-flow sensor (1); and
 - calculating the temperature of the subject (8) on the basis of the received temperature measurement values (T1, T2, T3, TV1, TV2).
- 45 7. A method according to claim 6, comprising the steps of
 - comparing temperature measurement values (T1, T2, T3) of the combined thermistor arrangements of the passive dual heat-flow sensor (1) to identify thermistors ($V_{\max}$) associated with a maximum vertical heat flow;
 - 50 - identifying the neighboring combined thermistors ($V_{\text{left}}, V_{\text{right}}$); and
 - calculating the temperature of the subject (8) on the basis of the temperature measurement values (T1, T2, T3) of those thermistors.
8. A method according to claim 6 or claim 7, comprising the step of averaging one or more temperature measurement values prior to calculating the temperature of the subject (8).
- 55 9. A method according to any of claims 6 to 8, comprising the steps of

- comparing temperature measurement values (T1, T2, T3) of the combined thermistor arrangements (S1, S2, S3) of the passive dual heat-flow sensor (1);
- identifying a combined thermistor arrangement (S1, S2, S3) providing unreliable temperature measurement values (T1, T2, T3); and
- discarding temperature measurement values (T1, T2, T3) collected by that combined thermistor arrangement (S1, S2, S3).

10. A temperature sensing arrangement (10) for monitoring the temperature of a subject (8), comprising

- a passive dual heat-flow sensor (1) according to any of claims 1 to 6; and
- an evaluation unit (2) arranged to receive temperature measurement values (T1, T2, T3, TV1, TV2) from the thermistors (S1, S2, S3, SV1, SV2) of the passive heat-flow sensor (1) and to calculate the temperature of the subject (8) on the basis of the received temperature measurement values (T1, T2, T3, TV1, TV2).

11. A temperature sensing arrangement according to claim 10, wherein the passive heat-flow sensor (1) comprises a wireless interface (5) for transmitting temperature measurement values (T1, T2, T3, TV1, TV2) to the evaluation unit (2).

12. A temperature sensing arrangement according to claim 10 or claim 11, wherein the passive heat-flow sensor (1) is realized as a wearable device.

13. A temperature sensing arrangement according to any of claims 10 to 12, wherein the evaluation unit (1) is realized as a portable device.

14. A temperature sensing arrangement according to any of claims 10 to 13, incorporated in a patient support device.

Patentansprüche

1. Passiver dualer Wärmestromsensor (1), umfassend eine Kontaktfläche (11) zur Platzierung auf einem Subjekt (8) während einer Temperaturüberwachungsmaßnahme;

- eine untere Schicht;
- eine obere Schicht;
- eine vertikale Thermistoranordnung (SV1, SV2), umfassend einen inneren Thermistor (SV1), der an der inneren Fläche der unteren Schicht des Sensors (1) angeordnet ist, und einen oberen Sensor (SV2), der an einer oberen Fläche der oberen Schicht des Sensors (1) angeordnet ist; und
- eine Vielzahl kombinierter Thermistoranordnungen, wobei eine kombinierte Thermistoranordnung Folgendes umfasst:
- einen inneren Thermistor (S1), der an einer inneren Fläche der unteren Schicht des Sensors (1) angeordnet ist;
- einen oberen Thermistor (S2), der an der oberen Fläche der unteren Schicht des Sensors (1) angeordnet ist und relativ zu dem inneren Thermistor (S1) angeordnet ist, um einen vertikalen Wärmestrom ausgehend von dem Subjekt (8) zu messen; und
- einen seitlichen Thermistor (S3), der in Übereinstimmung mit dem inneren Thermistor (S1) angeordnet ist, um einen horizontalen Wärmestrom entlang der Kontaktfläche (11) zu messen.

2. Passiver dualer Wärmestromsensor nach Anspruch 1, umfassend mindestens vier kombinierte Thermistoranordnungen.

3. Passiver dualer Wärmestromsensor nach Anspruch 1 oder Anspruch 2, umfassend eine Vielzahl vertikaler Thermistorpaare (S1, S2), wobei ein vertikales Thermistorpaar einen inneren Thermistor (S1) und einen oberen Thermistor (S2) umfasst.

4. Passiver dualer Wärmestromsensor nach einem der vorstehenden Ansprüche, wobei die äußere Oberfläche (12) des Sensors (1) freiliegt.

5. Passiver dualer Wärmestromsensor nach Anspruch 1, wobei die vertikale Thermistoranordnung (SV1, SV2) zentral in dem Wärmestromsensor (1) positioniert ist.

6. Verfahren zum Messen der Temperatur eines Subjekts (8) unter Verwendung eines passiven Wärmestromsensors (1) nach einem der Ansprüche 1 bis 5, wobei das Verfahren die folgenden Schritte umfasst:

- Platzieren der Kontaktfläche (11) des passiven Wärmestromsensors (1) an dem Subjekt (8) während einer Temperaturüberwachungsmaßnahme;
- Empfangen von Temperaturmesswerten (T1, T2, T3, TV1, TV2), die von den Thermistoren (S1, S2, S3, SV1, SV2) des passiven dualen Wärmestromsensors (1) gesammelt wurden; und
- Berechnen der Temperatur des Subjekts (8) auf der Basis der empfangenen Temperaturmesswerte (T1, T2, T3, TV1, TV2).

7. Verfahren nach Anspruch 6, das die folgenden Schritte umfasst:

- Vergleichen der Temperaturmesswerte (T1, T2, T3) der kombinierten Thermistoranordnungen des passiven dualen Wärmestromsensors (1), um mit einem maximalen vertikalen Wärmestrom assoziierte Thermistoren ($V_{\max}$) zu identifizieren;
- Identifizieren der benachbarten kombinierten Thermistoren (V_{links} , V_{rechts}); und
- Berechnen der Temperatur des Subjekts (8) auf der Basis der Temperaturmesswerte (T1, T2, T3) dieser Thermistoren.

8. Verfahren nach Anspruch 6 oder Anspruch 7, umfassend den Schritt des Mittelns eines oder mehrere Temperaturmesswerte vor dem Berechnen der Temperatur des Subjekts (8).

9. Verfahren nach einem der Ansprüche 6 bis 8, das die folgenden Schritte umfasst:

- Vergleichen von Temperaturmesswerten (T1, T2, T3) der kombinierten Thermistoranordnungen (S1, S2, S3) des passiven dualen Wärmestromsensors (1);
- Identifizieren einer kombinierten Thermistoranordnung (S1, S2, S3), die unzuverlässige Temperaturmesswerte (T1, T2, T3) bereitstellt; und
- Verwerfen von dieser kombinierten Thermistoranordnung (S1, S2, S3) gesammelter Temperaturmesswerte (T1, T2, T3).

10. Temperaturfühlanordnung (10) zum Überwachen der Temperatur eines Subjekts (8), die Folgendes umfasst:

- einen passiven dualen Wärmestromsensor (1) nach einem der Ansprüche 1 bis 6; und
- eine Auswertungseinheit (2), die angeordnet ist, um Temperaturmesswerte (T1, T2, T3, TV1, TV2) von den Thermistoren (S1, S2, S3, SV1, SV2) des passiven Wärmestromsensors (1) zu empfangen und die Temperatur des Subjekts (8) auf der Basis der empfangenen Temperaturmesswerte (T1, T2, T3, TV1, TV2) zu berechnen.

11. Temperaturfühlanordnung nach Anspruch 10, wobei der passive Wärmestromsensor (1) eine drahtlose Schnittstelle (5) zum Übermitteln von Temperaturmesswerten (T1, T2, T3, TV1, TV2) an die Auswertungseinheit (2) umfasst.

12. Temperaturfühlanordnung nach Anspruch 10 oder Anspruch 11, wobei der passive Wärmestromsensor (1) als tragbares Gerät ausgeführt ist.

13. Temperaturfühlanordnung nach einem der Ansprüche 10 bis 12, wobei die Auswertungseinheit (2) als portables Gerät ausgeführt ist.

14. Temperaturfühlanordnung nach einem der Ansprüche 10 bis 13, integriert in ein Patientenunterstützungsgerät.

Revendications

1. Capteur de flux thermique double passif (1) comprenant une face de contact (11) destinée à être placée sur un sujet (8) pendant une procédure de surveillance de température ;

- une couche inférieure ;
- une couche supérieure ;
- un agencement de thermistances vertical (SV1, SV2) comprenant une thermistance interne (SV1) agencée

sur une face interne de la couche inférieure du capteur (1) et un capteur supérieur (SV2) agencé sur une surface supérieure de la couche supérieure du capteur (1) ; et

- une pluralité d'agencements de thermistances combinées, dans lequel un agencement de thermistances combinées comprend

- une thermistance interne (S1) agencée sur une face interne de la couche inférieure du capteur (1) ;

- une thermistance supérieure (S2) agencée sur la surface supérieure de la couche inférieure du capteur (1) et agencée par rapport à la thermistance interne (S1) pour mesurer un flux thermique vertical s'échappant du sujet (8) ; et

- une thermistance latérale (S3) agencée en ligne avec la thermistance interne (S1) pour mesurer un flux thermique horizontal le long de la face de contact (11).

2. Capteur de flux thermique double passif selon la revendication 1, comprenant au moins quatre agencements de thermistances combinées.

3. Capteur de flux thermique double passif selon la revendication 1 ou la revendication 2, comprenant une pluralité de paires de thermistances verticales (S1, S2), dans lequel une paire de thermistances verticale comprend une thermistance interne (S1) et une thermistance supérieure (S2).

4. Capteur de flux thermique double passif selon l'une quelconque des revendications précédentes, dans lequel la surface extérieure (12) du capteur (1) est exposée.

5. Capteur de flux thermique double passif selon la revendication 1, dans lequel l'agencement de thermistances vertical (SV1, SV2) est positionné centralement dans le capteur de flux thermique (1).

6. Procédé de mesure de la température d'un sujet (8) à l'aide d'un capteur de flux thermique passif (1) selon l'une quelconque des revendications 1 à 5, lequel procédé comprend les étapes suivantes

- placement de la face de contact (11) du capteur de flux thermique passif (1) sur le sujet (8) pendant une procédure de surveillance de température ;

- réception de valeurs de mesure de température (T1, T2, T3, TV1, TV2) collectées par les thermistances (S1, S2, S3, SV1, SV2) du capteur de flux thermique double passif (1) ; et

- calcul de la température du sujet (8) sur la base des valeurs de mesure de température reçues (T1, T2, T3, TV1, TV2).

7. Procédé selon la revendication 6, comprenant les étapes suivantes

- comparaison des valeurs de mesure de température (T1, T2, T3) des agencements de thermistances combinées du capteur de flux thermique double passif (1) pour identifier les thermistances (V_{max}) associées à un flux thermique vertical maximal ;

- identification des thermistances combinées avoisinantes (V_{left} , V_{right}) ; et

- calcul de la température du sujet (8) sur la base des valeurs de mesure de la température (T1, T2, T3) de ces thermistances.

8. Procédé selon la revendication 6 ou la revendication 7, comprenant l'étape de calcul de la moyenne d'une ou plusieurs valeurs de mesure de température avant de calculer la température du sujet (8).

9. Procédé selon l'une quelconque des revendications 6 à 8, comprenant les étapes suivantes

- comparaison des valeurs de mesure de la température (T1, T2, T3) des agencements de thermistances combinées (S1, S2, S3) du capteur de flux thermique double passif (1) ;

- identification d'un agencement de thermistances combinées (S1, S2, S3) fournissant des valeurs de mesure de température non fiables (T1, T2, T3) ; et

- rejet des valeurs de mesure de température (T1, T2, T3) collectées par cet agencement de thermistances combinées (S1, S2, S3).

10. Agencement de détection de température (10) pour surveiller la température d'un sujet (8) comprenant

- un capteur de flux thermique double passif (1) selon l'une quelconque des revendications 1 à 6 ; et

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- une unité d'évaluation (2) agencée pour recevoir des valeurs de mesure de température (T1, T2, T3, TV1, TV2) des thermistances (S1, S2, S3, SV1, SV2) du capteur de flux thermique passif (1) et pour calculer la température du sujet (8) sur la base des valeurs de mesure de température reçues (T1, T2, T3, TV1, TV2).

- 5 **11.** Agencement de détection de température selon la revendication 10, dans lequel le capteur de flux thermique passif (1) comprend une interface sans fil (5) pour transmettre les valeurs de mesure de température (T1, T2, T3, TV1, TV2) à l'unité d'évaluation (2).
- 10 **12.** Agencement de détection de température selon la revendication 10 ou la revendication 11, dans lequel le capteur de flux thermique passif (1) est réalisé sous la forme d'un dispositif portable.
- 15 **13.** Agencement de détection de température selon l'une quelconque des revendications 10 à 12, dans lequel l'unité d'évaluation (2) est réalisée sous la forme d'un dispositif portatif.
- 20 **14.** Agencement de détection de température selon l'une quelconque des revendications 10 à 13, incorporé dans un dispositif de support patient.

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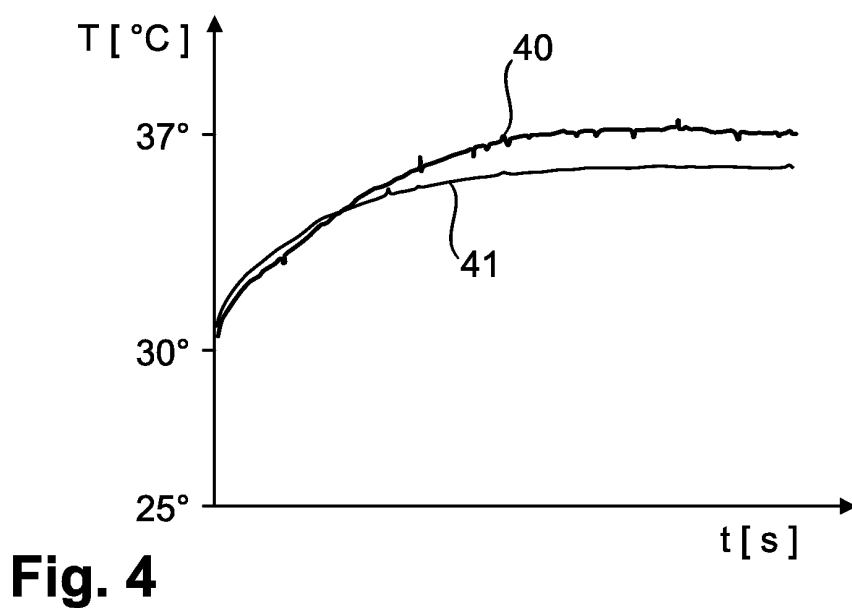
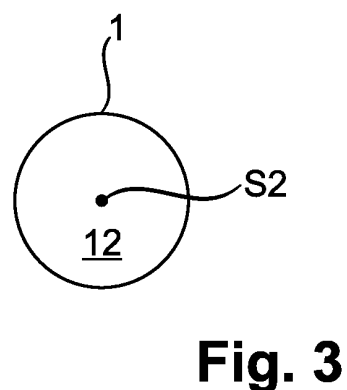
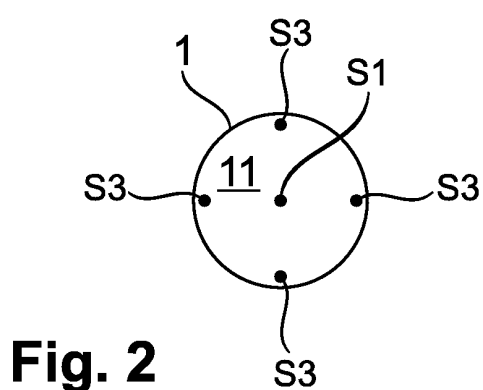
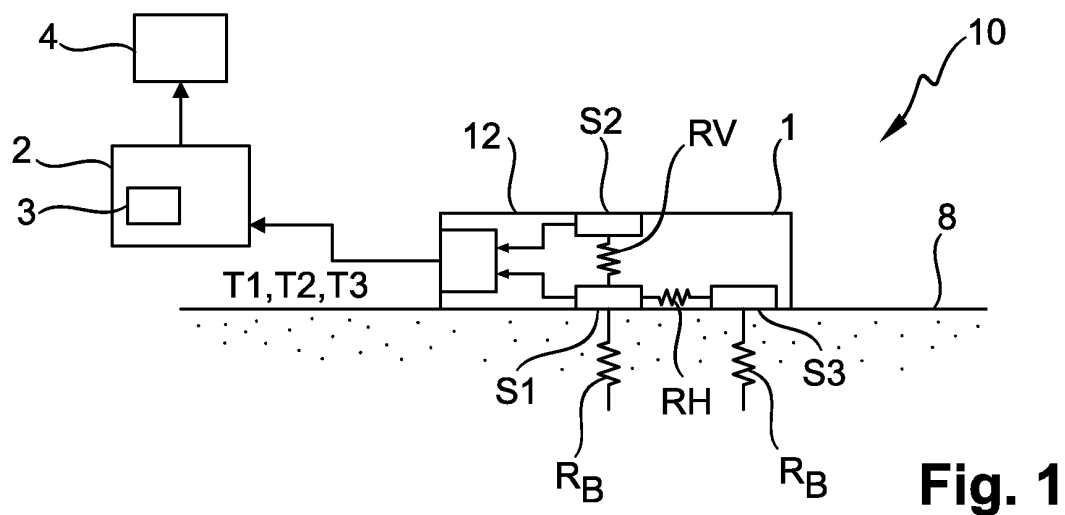
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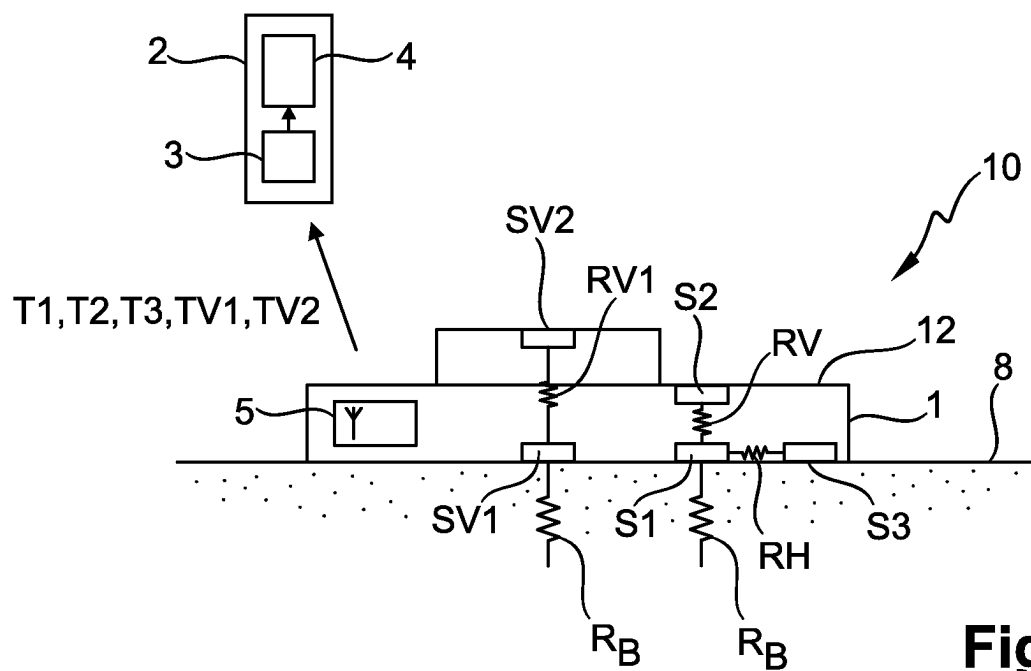


Fig. 5

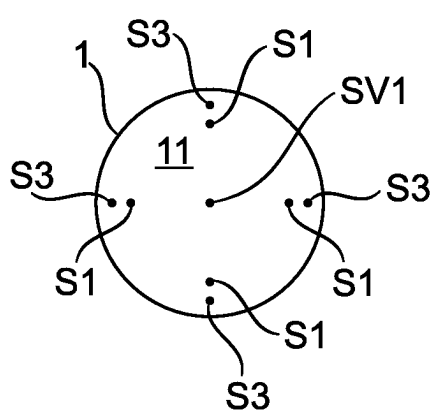


Fig. 6

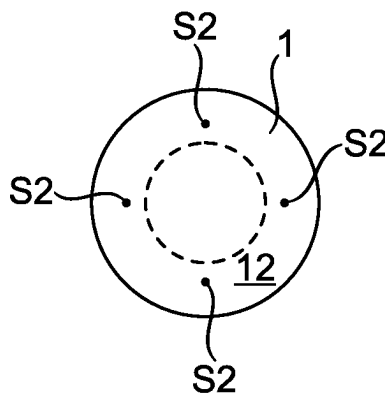


Fig. 7

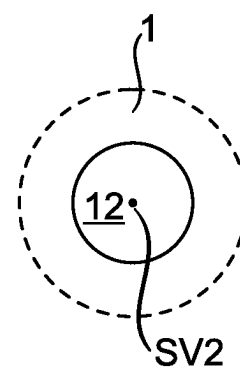


Fig. 8

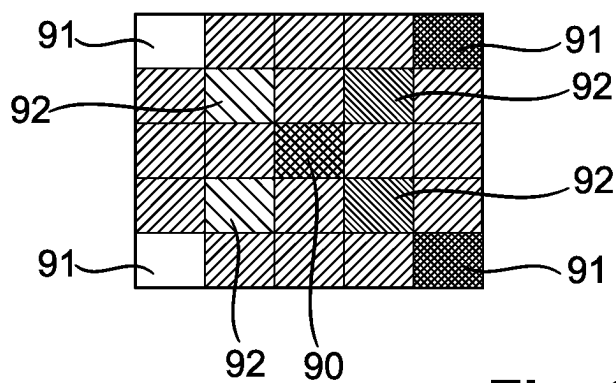


Fig. 9

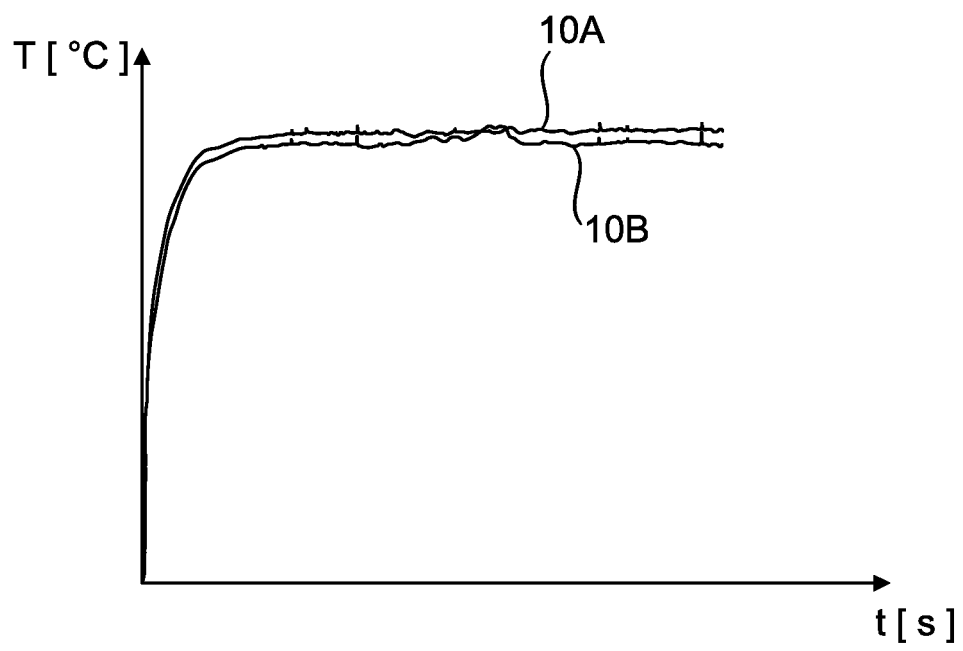


Fig. 10

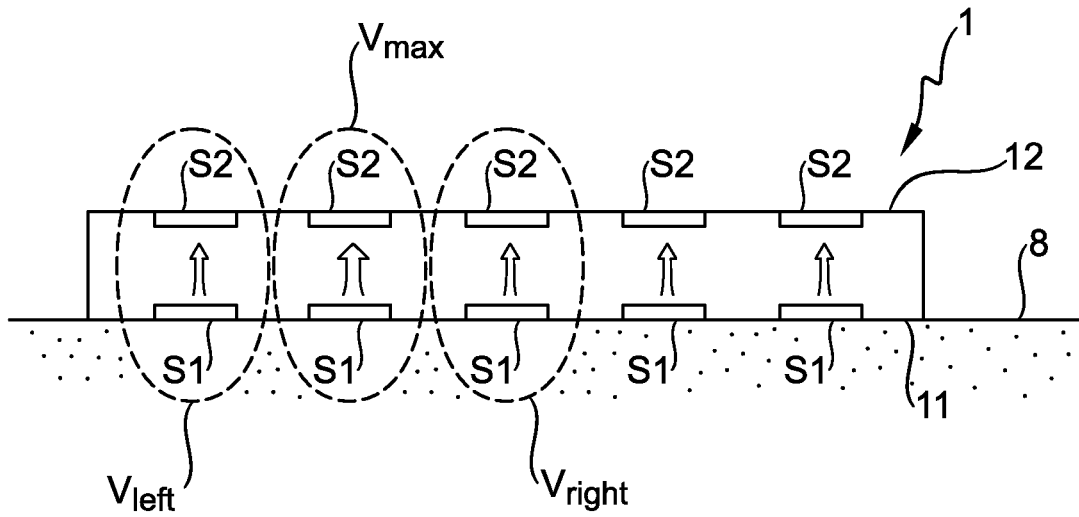


Fig. 11

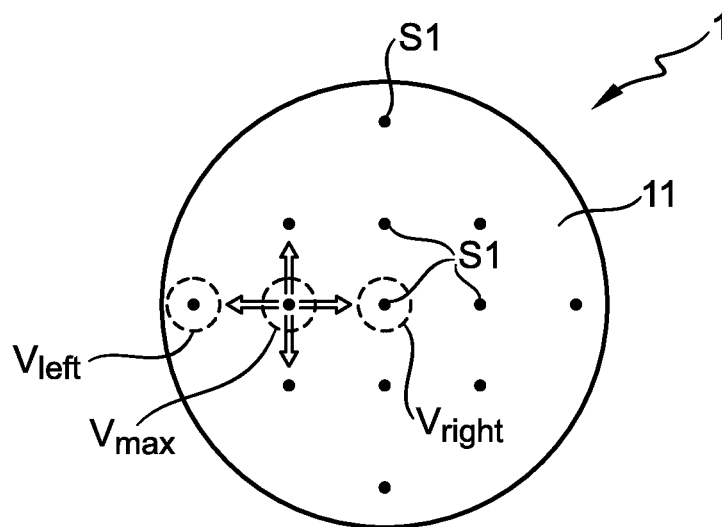


Fig. 12

REFERENCES CITED IN THE DESCRIPTION

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专利名称(译)	热流量传感器		
公开(公告)号	EP3394580B1	公开(公告)日	2019-11-27
申请号	EP2016826324	申请日	2016-12-21
[标]申请(专利权)人(译)	皇家飞利浦电子股份有限公司		
申请(专利权)人(译)	皇家飞利浦N.V.		
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IPC分类号	G01K1/16 G01K13/00 G01K7/42 A61B5/00 A61B5/01		
CPC分类号	A61B5/002 A61B5/01 A61B2505/05 A61B2562/0271 A61B2562/046 G01K1/165 G01K7/427 G01K13/002		
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优先权	2015201450 2015-12-21 EP		
其他公开文献	EP3394580A1		
外部链接	Espacenet		

摘要(译)

本发明描述了一种无源热流传感器（1），其包括用于在温度监测过程中放置在对象（8）上的接触面（11）；多个组合热敏电阻装置，其中，组合热敏电阻装置包括：内部热敏电阻（S1），其布置在传感器（1）的内表面；上部热敏电阻（S2）布置在传感器（1）的上表面并且相对于内部热敏电阻（S1）布置，以测量从对象（8）向外的垂直热流；相对于内部热敏电阻（S1）布置的横向热敏电阻（S3）以测量沿接触面（11）的水平热流。本发明还描述了一种使用热流传感器（1）测量对象（8）的温度。温度感测装置（10），其使用热流量传感器（1）监视被摄体（8）的温度。

$$T_{db} = T1 + \left[\frac{\frac{T1-T2}{RV} + \frac{T1-T3}{RH}}{R_B} \right] \quad (1)$$